(India Region)

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www.ipc.org/ipc-india

Deliver on Consistency, Reliability and Quality



Volume 2

I'm happy to note the progress of India region Standard Development activities.

In only our third quarter of Standard development activities, IPC's India region is now maturing with EMS - IPC 610 (7-31B-IND), JSTD001 (5-22A-IND) and Wire Harness (IPC 620 - 7-31F-IND) regional task groups. Successful productive meetings for two design related project initiations (PINs) are now approved for development.

One of the major achievement during last quarter was the release of the draft version of the Automotive Supplier Check sheet at IPC India flagship IEMI event. This Check Sheet is intended to minimize the variance in auditing practices of OEM's at supplier sites, thereby

enabling suppliers to focus resources on process improvement and product reliability. The Check Sheet will also help PCBA suppliers understand and be better prepared for automotive requirements which is again truly demonstrates IPC objectives of helping 'Build Electronics Better'.

I congratulate team efforts from India for the progress and wish to engages in IPC's global standardization platform too. I look forward to many future successes.

Standard Development Meetings at IEMI 2023

A series of Standards Development meetings conducted during IPC India flagship event (IEMI 2023) at Chennai (1st Aug.) and Pune (3rd Aug.). During these meetings, project team members from various cities physically met in the presence of VP - Standards (Mr. David Bergman) and President & CEO (Mr. John Mitchell) and President - Europe & South Asia Operations (Mr. Sanjay Huprikar), ED - IPC India (Mr. Gaurab Majumdar) also joined to take a note of the progress and appreciated on the progress made during last three quarters of year 2023.



greeting the India Regional Task Team



IPC 610 (7-31B-IND), J-STD-001 (5-22A-IND)



IPC/WHMA 620 (7-31F-IND)



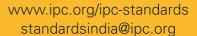
Guideline for Printed Board Design and Manufacturing of IOT Products



Project Team: Guideline for Automotive Electronics Printed Board Thermal Management & Electronic Component Derating



(India Region)







IPC Automotive Supplier Check Sheet



The IPC Automotive Supplier Certification check sheet is a key project undertaken by the Indian expert's team from various automotive organizations. The draft version of the same check sheet is been released during IEMI event at Pune (3rd Aug.).

This check sheet does not add or replace any of the existing IPC standards but rather reinforces them in a cohesive way to help the electronics manufacturing industry to "Build Electronics Better".

PURPOSE

- To minimize variance in auditing practices of OEM's at supplier sites, thereby enabling suppliers to focus resources on process improvement and product reliability.
- To help PCBA suppliers understand and be better prepared for automotive requirements

EXPECTED BENEFIT

- Audits become more efficient and purposeful.
- Reduces efforts of suppliers in preparing for varying needs of audits, thereby releasing time for value-adding continuous improvement.
- Leverages the experience of industry players, both OEM's and suppliers in order to "build electronics better".
- Combines the knowhow built into already popular IPC standards that have been in use over the years in a more comprehensive and coordinated manner.
- Results in better understanding and more fruitful cooperation between respective OEM's and suppliers.

NEXT ACTIONS

- Obtain feedback from various automotive OEMs and Suppliers
- Release/ Launch of Check Sheet on 21st Nov. in presence of Indian and Global Automotive OEMs and Suppliers.

IPC WINTERCOM

STANDARDS DEVELOPMENT COMMITTEE MEETINGS

January 22-25, 2024

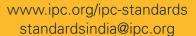
Barcelona, Spain

Wintercom event is scheduled first time in Europe (Barcelona, Spain) during Jan 22-25, 2024. In this event, various Standard Development task teams related to EMS, Wire Harness, Design etc. will be gathered to discuss on the next actions. IPC India is also going to participate in this event for the first time along with key India members.





(India Region)







IPC Volunteer Awards

Currently IPC India is engaged with 5 Standard Development project teams consisting with 66 volunteers from 57 prominent organizations of India, Sri Lanka and Israel. These team are soon to be expended from volunteers from Missile East, South Africa, Malaysia, Thailand and Saudi Arabia. IPC recognized the efforts from these volunteers for their exemplary efforts and engagement towards industry benefits.



IPC-A- 610 (7-31B-IND) and J-STD 001 (5-22A-IND) India Regional Task Group



IPC/ WHMA-A-620 (7-31F-IND) India Regional Task Group



Sumi MS Centum Electronics Ltd.- Bangalore



Siraj Puthanpurayil Schneider Electric IT Business India Pvt. Ltd., Bangalore.



Venkatachalam MNM on behalf of Santosh B Sasmos HET Technologies Ltd., Bangalore.



Yogesh Singh Precision Electronics Ltd., Noida



Darshana.M.J. Tata Advanced Systems Ltd., Bangalore.



Sanjeev Kumar ADI Electronics Manufacturing Technologies Pvt. Ltd., Bangalore



MTAR Technologies Ltd., Hyderabad



Husanpal Bhela Vista Consoles Electronics Pvt. Ltd., Noida



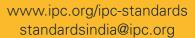
Gurudatta GS



Astra Microwave Products Ltd., Bangalore | Amphenol Interconnect India Pvt. Ltd., Bangalore



(India Region)







Standards: Current Status

Published Standards

IPC-2591, Version 1.7	Connected Factory Exchange (CFX)
IPC-9797A	Press-fit Standard for Automotive Requirements and other High-Reliability Applications
IPC-7352	Generic Guideline for Land Pattern Design

Final Draft for Industry Review

IPC-1791D	Trusted Electronic Designer, Fabricator and Assembler Requirements
IPC-4562B	Metal Foil for Printed Board Applications
IPC-6018D Amendment 1	Qualification and Performance Specification for High Frequency (Microwave) Printed Boards
IPC-A-610J	Acceptability of Electronic Assemblies
IPC-A-630A	Acceptability Standard for Manufacture, Inspection, and Testing of Electronic Enclosures
J-STD-001J	Requirements for Soldered Electrical and Electronic Assemblies
J-STD-609C	Marking and Labelling of Components, PCBs and PCBAs to Identify Lead (Pb), Lead-Free (Pb-free) and Other Attributes

Project Approved

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IPC-2201	Requirements for Physics of Failure Analysis for Components and Assemblies
IPC-2611A	Generic Requirements for Electronic Product Documentation
IPC-2612-1A	Sectional Requirements for Electronic Diagramming Symbol Generation Methodology
IPC-2612A	Sectional Requirements for Electronic Diagramming Documentation (Schematic and Logic Descriptions)
IPC-4556A	Specification for Electroless Nickel/Electroless Palladium/ Immersion Gold (ENEPIG) Plating for Printed Boards
IPC-4557	Specification for Electrolytically Deposited Nickel/Gold Surface Finish for Printed Board Applications
IPC-6905	Qualification and Performance Specification for Additively Manufactured Electronics (AME)
IPC-6911	Acceptability of Additively Manufactured Electronics (AME)
IPC-6931	Requirements and Acceptance of Optical Module Printed Boards
IPC-7070	Guidelines for Printed Board Component Mounting
IPC-9205	Evaluating Electrochemical Performance of Electronics Manufacturing Materials and Processes
IPC-HDBK-001A	Handbook and Guide to Supplement J-STD-001G and J-STD-001G - Revision A
IPC-HDBK-850A	Guidelines for Design, Selection and Application of Potting Materials and Encapsulation Processes Used for Electronics Printed Circuit Board Assembly
IPC/JEDEC J-STD-033E	Handling, Packing, Shipping and Use of Moisture, Reflow, and Process Sensitive Devices
IPC/JEDEC J-STD-609C	Marking, Symbols, and Labels of Leaded and Lead-Free Terminal Finished Materials Used in Electronic Assembly
J-STD-001JA/IPC-A-610JA	Automotive Addendum to IPC J-STD-001J Requirements for Soldered Electrical and Electronic Assemblies and IPC-A-610J Acceptability of Electronic Assemblies



For more information, please contact:

Mr. Saurabh K Saxena (IPC Liaison @ IPC India) for any clarifications on India Standard Development activities.